Amendments to the Specification:

Please replace the first full paragraph on page 2, lines 3-10, with the following replacement paragraph:

In the case of a conventional general substrate fabricating line, processing of printing cream solder on a bare substrate is first performed in a solder printing machine and then the substrate is sent to a high-speed mounter and [[a]] an odd-shape mounter in order to mount the above various components. Moreover, the substrate after mounting components is sent to a reflow furnace to undergo soldering.

Please replace the sixth full paragraph on page 20, lines 18-20, with the following replacement paragraph:

Figs. ~~5(1)~~ 5A and ~~5(2)~~ 5B show illustrations showing set examples of criterion values used for component fly inspection.

Please replace the third full paragraph on page 21, lines 9-18, with the following replacement paragraph:

In the first step A, cream solder is printed on a printed circuit board by a solder printing machine. In the next step B, the solder-printed substrate is supplied to a high-speed mounter to mount a chip component. Moreover, in the step C, the substrate undergoing the step B is supplied to [[a]] an odd-shape mounter to mount odd-shaped components such as BGA, CSP, and IC. In the final step D, the component-mounted substrate is sent into a reflow furnace to heat the substrate and fix each component on the substrate.

Please replace the paragraph bridging pages 25 and 26 (page 25, line 12 to page 26, line 2), with the following replacement paragraph:

The substrate inspection data storing section 609 is a memory for storing the substrate inspection data set for each type of substrate. Each substrate inspection data is constituted by storing the component inspection data for a chip component mounted on a corresponding substrate by a front-stage high-speed mounter in a data file provided with a predetermined file name (hereafter referred to as "inspection data file"). Moreover, the inspection data file of this embodiment stores inspection data for inspection for determining whether a chip

component flies to the mounting position of [[a]] an odd-shaped component to be mounted by the next odd-shape mounter (this is the component fly inspection previously described). Details of the component-fly inspection data will be described later.

Please replace the second full paragraph on page 29, lines 14-23, with the following replacement paragraph:

Fig. 4 shows a distribution of inspecting windows same as the above inspecting window. In Fig. 4, a small rectangle 81 drawn by a thin line denotes a window for inspecting a component mounted on a chip component, which is constituted by the component body window w1 for each chip component. A rectangle 82 drawn by a thick line, however, denotes a window for inspecting the component fly, which is constituted by the window w2 obtained by enlarging the component body window w1 for [[a]] an odd-shaped component.

Please replace the first full paragraph on page 30, lines 5-7, with the following replacement paragraph:

~~Fig. 5 shows~~ Figs. 5A and 5B show a set example of a criterion value for performing determination processing according to the size of a component in component fly inspection.

Please replace the second full paragraph on page 30, lines 8-16, with the following replacement paragraph:

When component fly occurs, the flied chip component is in a state of turning to any direction. Therefore, in the case of this embodiment, a circumscribing rectangle RT is set for a prospective image of a component extracted in accordance with a binary threshold value as shown in Fig. ~~5(2)~~ 5A so as to express the size of the component by the length of the major side W (W is hereafter referred to as "component width W") of the rectangle RT.

Please replace the paragraph bridging pages 30 and 31 (page 30, line 17 to page 31, line 4), with the following replacement paragraph:

Moreover, in the case of this embodiment, the criterion value for the component width W is expressed by a ratio to the length L shown in Fig. ~~5(1)~~ 5B. The length L denotes the length of the diagonal line of the image of a chip component, which is previously obtained by

measuring the image of a model chip component. Because the ratio to the length L depends on the direction of the flied component, the minimum value L1 and maximum value L2 of the fluctuating numerical value range are set as criterion values in this embodiment. That is, when the prospective image of the component extracted in the inspecting window is a chip component, the component width W satisfies the condition of $L1 \leq W \leq L2$.

Please replace the paragraph bridging pages 35 and 36 (page 35, line 21 to page 36, line 10), with the following replacement paragraph:

An image sent from the imaging section 2 is output to the displaying section 611 through the image inputting section 602 and CPU 601. The operator sets an inspecting window, binary threshold value, and criterion value in order every portion to be inspected while confirming the image display at the displaying section 611 (ST104, ST105, and ST106). In this case, when a portion to be inspected is a chip-component mounting position, the inspection data specific to a chip component to be mounted is set in ST104 to ST106. However, when a portion to be inspected is [[a]] an odd-shaped-component mounting position, in ST104 to ST106, binary threshold values for extracting a plurality of colors and criterion values corresponding to a plurality of sizes are set in order to execute the above component fly inspection.

Please replace the third full paragraph on page 39, lines 11-25, with the following replacement paragraph:

In ST208, ~~potions~~ portions to be inspected on an image are noticed in an optional sequence to execute the inspection corresponding to each portion. That is, when a noticed portion is the mounting position of a chip component, mounted component inspection of the chip component is executed and when a ~~notice~~ noticed portion is the mounting position of [[a]] an odd-shaped component, component fly inspection is executed. In the case of actual substrate inspection, a plurality of times of imaging is frequently performed while changing imaging positions. However, as described above, according to the processing of executing two types of inspections by mixing them, it is possible to input the next image after processing all inspecting windows included in the same image and execute efficient inspections.

Please replace the first full paragraph on page 40, lines 1-11, with the following replacement paragraph:

When inspections for all portions to be inspected are completed, ST208 is completed and ST209 is started to output the inspection results to the displaying section 611 and transceiving section 613. In the next ST210, substrates to be inspected are brought out to the line at [[a]] an odd-shape mounter. Thereafter, when there is a substrate to be next inspected, ST203 is restarted to start the inspecting procedure for the next substrate. The procedure for returning to ST203 from ST209 to ST211 and ST211 is the same as the case in which the other condition 1 or 2 is selected.

Please replace the paragraph bridging pages 43 and 44 (page 43, line 21 to page 44, line 3), with the following replacement paragraph:

Moreover, though a region to be inspected for component fly inspection is restricted to a region corresponding to the mounting position of [[a]] an odd-shaped component in the case of the above embodiment, without being restricted to the above mentioned, it is also allowed to executed component fly inspection for the whole image excluding the mounting position of a chip component.